

Table 6: Description of Digital Patent (H04N5/22~25:33~36, H01L27/146~148)

IPC	Descriptions
• H	ELECTRICITY
• H04	ELECTRIC COMMUNICATION TECHNIQUE
• H04N	PICTORIAL COMMUNICATION, e.g. TELEVISION
• H04N5/00	Details of television systems
• H04N5/222	Studio circuitry; Studio devices; Studio equipment
• H04N5/225	Television cameras
• H04N5/228	Circuit details for pick-up tubes
• H04N5/232	Devices for controlling television cameras, e.g. remote control
• H04N5/235	Circuitry {or methods} for compensating for variation in the brightness of the object
• H04N5/238	by influencing the optical part of the camera
• H04N5/243	by influencing the picture signal
• H04N5/247	Arrangements of television cameras
• H04N5/253	Picture signal generating by scanning motion picture films or slide opaques, e.g. for telecine
• H04N5/257	Picture signal generators using flying-spot scanners
• H04N5/33	Transforming infra-red radiation
• H04N5/335	using solid-state image sensors
• H04N5/341	Extracting pixel data from an image sensor by controlling scanning circuits
• H04N5/343	by switching between different modes of operation using different resolutions or aspect ratios
• H04N5/345	by partially reading an SSIS array
• H04N5/347	by combining or binning pixels in SSIS
• H04N5/349	for increasing resolution by shifting the sensor relative to the scene
• H04N5/351	Control of the SSIS depending on the scene
• H04N5/353	Control of the integration time
• H04N5/355	Control of the dynamic range
• H04N5/357	Noise processing, e.g. detecting, correcting, reducing or removing noise
• H04N5/359	applied to excess charges produced by the exposure
• H04N5/361	applied to dark current
• H04N5/363	applied to reset noise, e.g. KTC noise
• H04N5/365	applied to fixed-pattern noise, e.g. non-uniformity of response
• H04N5/367	applied to defects, e.g. non-responsive pixels
• H04N5/369	SSIS architecture; Circuitry associated therewith
• H01	BASIC ELECTRIC ELEMENTS
• H01L	SEMICONDUCTOR DEVICES; ELECTRIC SOLID STATE DEVICES NOT OTHERWISE PROVIDED FOR
• H01L27/00	Devices consisting of a plurality of semiconductor or other solid-state components formed in or on a common substrate
• H01L27/146	Imager structures
• H01L27/148	Charge coupled imagers